

Chip on Board

HW27U-HF

WIRE BONDER

KXF-3E2H

A COB wire bonder for flexible performance
 and for wider-area bonding



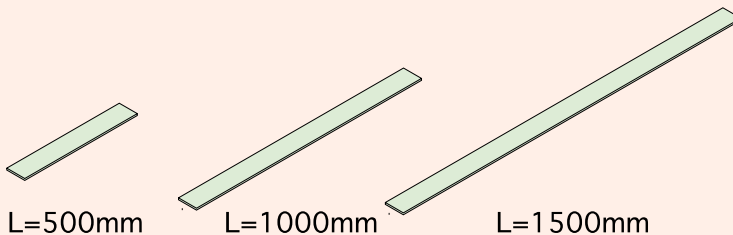
- High speed bonding:0.15 s/wire
- High-reliability with US monitor [optional] and gray-scale recognition
- Easy-to-operate color display
- Great variety of wire bonding techniques
 - Chip to chip,Lead to lead,Staggered wiring
 - Support for small balls
 - Bonding data is changeable for each wire

Model name	HW27U-HF
Model No.	KXF-3E2H
Cycle time	non-loop control:0.15 s /wire (Loop length 2 mm) loop control:0.17 s /wire (Loop length 2 mm)
Bonding accuracy	±5 μm (In 6x lens and gray-scale recognition)
Substrate dimensions	L 50 mm × W 20 mm to L 310 mm × W 100 mm
Bonding area	End-face clamp: Max. L 115 mm × W 95 mm Mask type: Max. L 115 mm × W 83 mm
Bonding method	Gold bonding method using both ultrasonic and thermocompression bonding
Electric source	Single phase AC 200 V ±10 V, 2.5 kVA
Pneumatic source	440 kPa, 50 L/min [Standard]
Dimensions	W 1 510 mm × D 880 mm × H 1 510 mm
Mass	550 kg

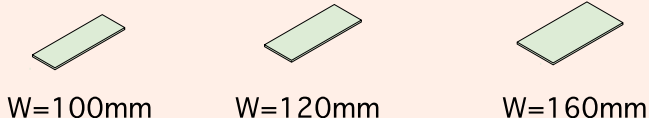
※Values such as cycle time and bonding accuracy may vary depending on operating conditions.
 ※Please refer to the specifications on details.

Wire bonding for a wide variety of boards

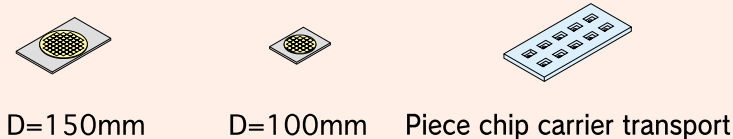
Printer head, Image sensor, etc.



Communication, Audio Visual, Car electronics, device, etc.

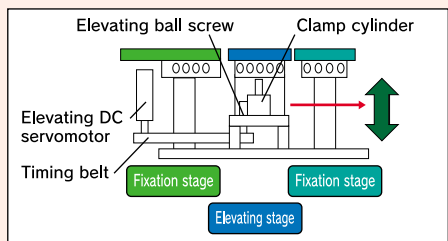
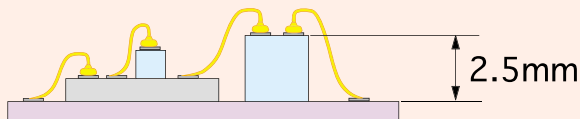


Wafer bump, Chip bump



Support for the great-step-height bonding of electronic components

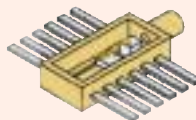
- Tilt-less high-quality bonding in spite of great step height
- High-precision bonding through the recognition of great step height



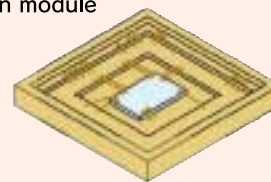
Z-axis elevating module



Optical-communication module



Optical-communication module



CCD image sensor

⚠ Safety Cautions

To ensure safety when using this equipment, all work should be performed according to that as stated in the separate Operating Instructions. Read your operating instructions manual thoroughly.

<http://panasonic.co.jp/pfsc/en/>

Inquiries...

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